2SJ0674

Silicon P-channel MOS FET

For switching circuits

■ Features

- Low ON resistance Ron
- High-speed switching
- SSSMini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Drain-source surrender voltage	V _{DSS}	-30	V	
Gate-source surrender voltage	V _{GSS}	±12	V	
Drain current	I_D	-100	mA	
Peak drain current	I_{DP}	-200	mA	
Power dissipation	P_{D}	100	mW	
Channel temperature	T _{ch}	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

■ Package

Code

SSSMini3-F1

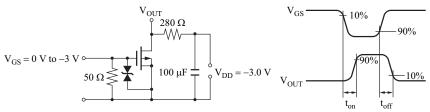
- Pin Name
 - 1: Gate
 - 2: Source
 - 3: Drain
- Marking Symbol: 5U

■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	V _{DSS}	$I_D = -10 \mu\text{A}, V_{GS} = 0$	-30			V
Drain-source cutoff current	I_{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0$			-1.0	μА
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$			±10	μΑ
Gate threshold voltage	V _{TH}	$I_D = -1.0 \mu A, V_{DS} = -3.0 V$	- 0.5	-1.0	-1.5	V
Drain-source ON resistance	D	$I_D = -10 \text{ mA}, V_{GS} = -2.5 \text{ V}$		13	30	Ω
	R _{DS(on)}	$I_D = -10 \text{ mA}, V_{GS} = -4.0 \text{ V}$		9	18	
Forward transfer admittance	Y _{fs}	$I_D = -10 \text{ mA}, V_{DS} = -3 \text{ V}, f = 1 \text{ kHz}$	20	40		mS
Short-circuit input capacitance (Common source)	C _{iss}	$V_{DS} = -3 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		12		pF
Short-circuit output capacitance (Common source)	C _{oss}			13		pF
Reverse transfer capacitance (Common source)	C _{rss}			7		pF
Turn-on time *	t _{on}	$V_{DD} = -3 \text{ V}, V_{GS} = 0 \text{ V to } -3 \text{ V}, I_D = -10 \text{ mA}$		300		ns
Turn-off time *	t _{off}	$V_{DD} = -3 \text{ V}, V_{GS} = -3 \text{ V to } 0 \text{ V}, I_D = -10 \text{ mA}$		400		ns

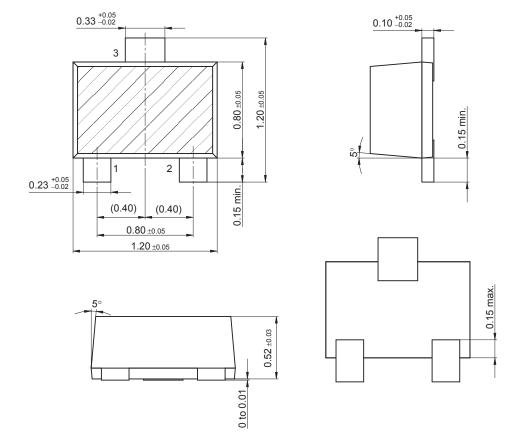
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: t_{on} , t_{off} measurement circuit



SSSMini3-F1

Unit: mm



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